PCN Number:		20211202000.2					PCN Date	December 17, 2021
Title:		Bubble Wrap removal for Select MSL1 Device(s)						
Customer Contact:		PCN Manager					Dept:	Quality Services
Proposed 1 st Ship Date:		June 17, 2022			Estimated Sample Samples not supported			
Change Type:								
Assembly Site				Design			Wafer Bump Site	
	Assembly Process			Data Sheet			Wafer Bump Material	
Assembly Materials			Part number change			Wafer Bump Process		
Mechanical Specification			Test Site			Wafer Fab Site		
□ Packing/Shipping/Labeling			Test Process			Wafer Fa	ab Materials	
							Wafer Fab Process	
PCN Details								

PCN Details

Description of Change:

This change notification is to announce the Bubble wrap removal for select MSL1 devices listed in the "Product Affected" Section.

	From	То
Packing Description	With Bubble Wrap	Without Bubble Wrap
Visual comparison		AMERICA STATE STATE OF THE PARTY OF THE PART

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings or to the associated device component Test Reports.

RoHS	REACH	Green Status	IEC 62474
	□ No Change		

Changes to product identification resulting from this PCN:

None.

Product Affected:					
PTCA6408AQPWRQ1	SN74HCS30QDRQ1	TLIN10283DRQ1	TLIN2021DRQ1		
SN74HC74QDRG4Q1	TCAN1044DRQ1	TLIN10283SDRQ1			
SN74HC74QDRQ1	TCAN1044VDRQ1	TLIN10285DRQ1			
SN74HCS164QDRQ1	TLIN1021DRQ1	TLIN10285SDRQ1			

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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